



SCH400-AA

IEC 61850-3, IEEE1613 Substation 2U Computer



Power Automation Computer

- Intel 10th Gen Xeon® W-1200/ Core i Processor
- 4 x DDR4 up to 128GB
- 2 x RJ45 GbE LAN, 2 x RJ45 10GbE LAN (by option), 1 x IPMI, 4 x USB3.2, 2 x USB2.0, 2 x DP, 1 x VGA, 1 x DVI-D
- 4 x 2.5" Easy swap SSD/HDD Tray (Support RAID 0,1,5,10)
- 3 x PCIe Expansion Slots
- TPM Support / FTDI By option
- 9~36V DC-IN 2 x 200W Redundant PSU

Specifications

System

CPU	10th Generation Intel® Xeon® W-1200 Processors Intel® Xeon® W-1290TE Processor (20M Cache, up to 4.50 GHz) Intel® Xeon® W-1250TE Processor (12M Cache, up to 3.80 GHz) 10th Generation Intel® Core™ i9/i7/i5 Processors Intel® Core™ i9-10900TE(20M Cache, up to 4.60 GHz) Intel® Core™ i7-10700TE(16M Cache, up to 4.50 GHz) Intel® Core™ i5-10500TE(12M Cache, up to 3.70 GHz)
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Memory type	4 x DDR4 up to 128GB
Expansion Slot	1 PCI-E 3.0 x16 2 PCI-E 3.0 x4
Storage Device	4 x 2.5" Easy swap HDD/SSD Tray (Support RAID 0,1,5,10)

Rear I/O

Power Button	1 x w/Indicator LED
USB	2 x USB 2.0

Front I/O

Power Input	9~36V DC IN
LAN	2 x RJ45 GbE LAN ; 2 x RJ45 10GbE LAN (By option) ; 1 x IPMI
USB	4 x USB 3.2
DisplayPort	2 x DP
DVI	1 x DVI-D
VGA	1

Power

Power Input	9~36V DC-IN, 2 x 150W DC/DC Redundant Power Supply
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Security

TPM	1
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Management

FTDI	1 (By option)
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OS support list

Windows Windows 10 x64

Linux Ubuntu, Red Hat

Mechanical and Environmental

Dimension 430 x 450 x 88 mm (W x D x H)

Operating Temp. -20 to 60°C

Storage Temp. -40°C to 85°C

Relative Humidity 5% to 95%, non-condensing

Standards CE, FCC, MIL-STD 810G Compliance

System Design Fanless

Mounting 2U Rackmount

MIL-STD-810G Method 507.5, Procedure II (Temperature & Humidity)
Method 516.6 Shock-Procedure V Non-Operating (Mechanical Shock)
Method 516.6 Shock-Procedure I Operating (Mechanical Shock)
Method 514.6 Vibration Category 24/Non-Operating (Category 20 & 24, Vibration)
Method 514.6 Vibration Category 20/Operating (Category 20 & 24, Vibration)
Method 501.5, Procedure I (Storage/High Temperature)
Method 501.5, Procedure II (Operation/High Temperature)
Method 502.5, Procedure I (Storage/Low Temperature)
Method 502.5, Procedure II (Operation/Low Temperature)
Method 503.5, Procedure I (Temperature shock)

EMC CE, FCC compliant

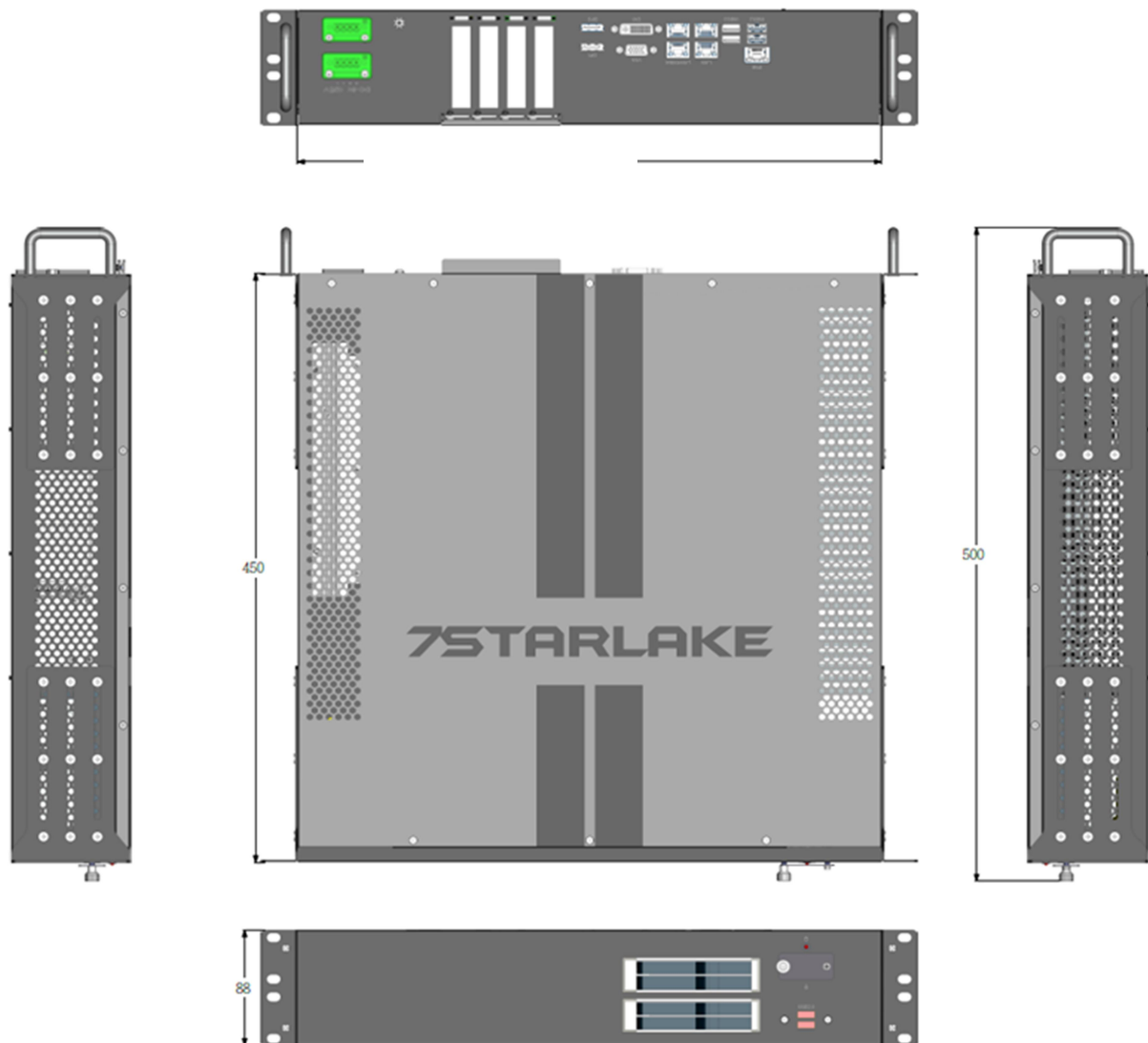
Green Product RoHS, WEEE compliance

Ordering Information

SCH400-BB

2U 19" Power Automation Fanless Server Computer with Intel 10th Gen Xeon® W-1200 or Core™ i9/i7/i5 Processor, 2 × RJ45 GbE, 1 x IPMI, 9~36 V DC-IN, 2 x 150W Redundant Power Supply, TPM Support/FTDI By option, Operating Temperature -30~+70°C

Dimension



Front Panel I/O Placement



Rear Panel I/O Placement

